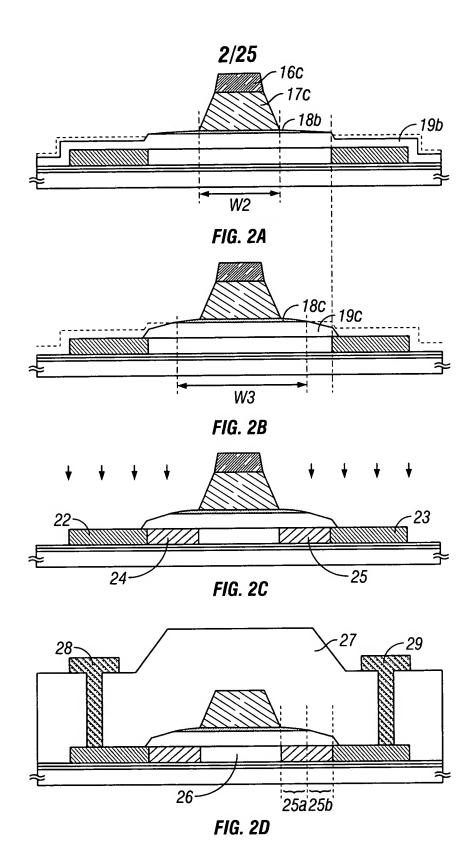
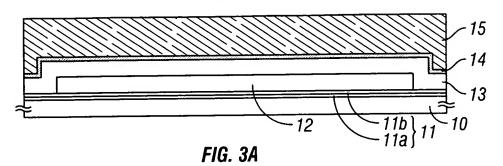


FIG. 1D





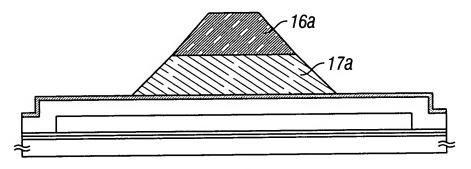


FIG. 3B

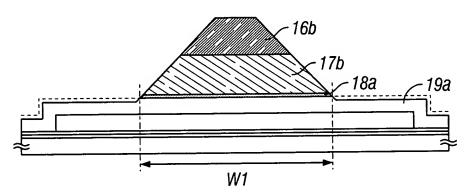


FIG. 3C

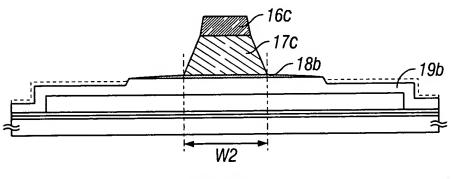
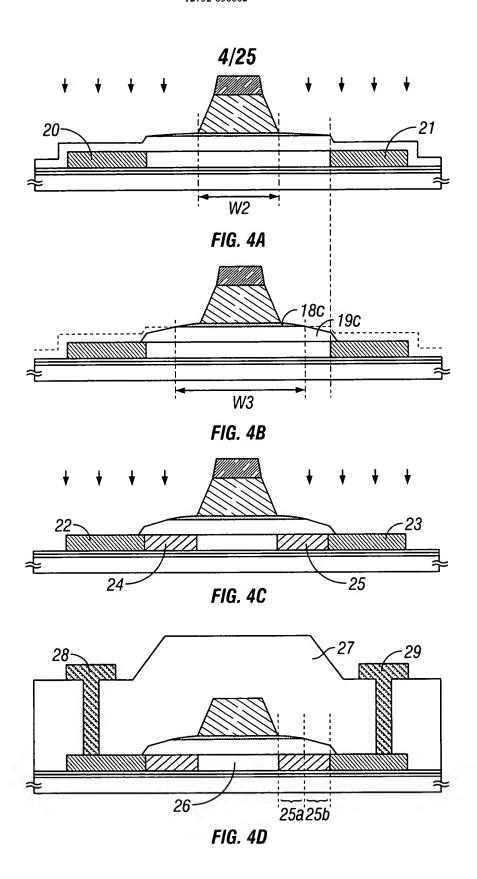
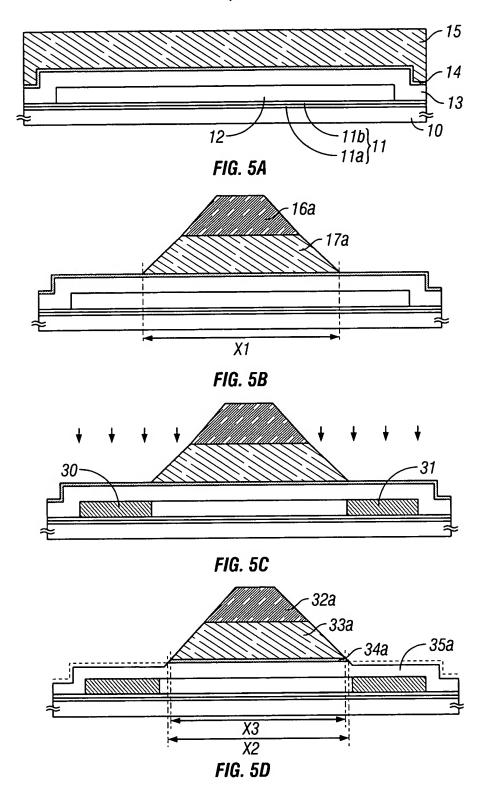
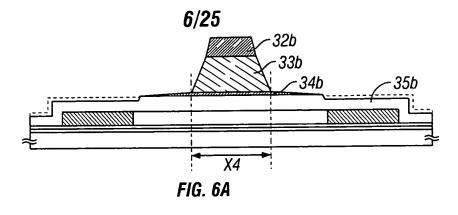
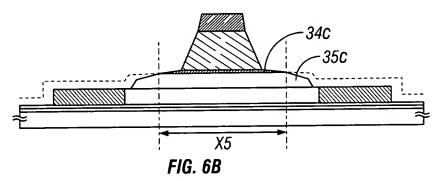


FIG. 3D









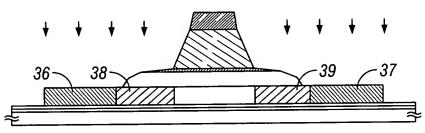
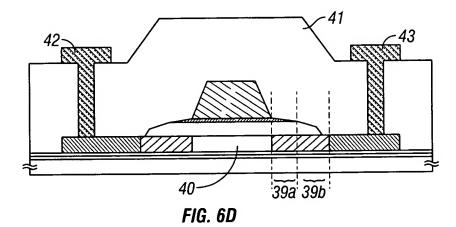
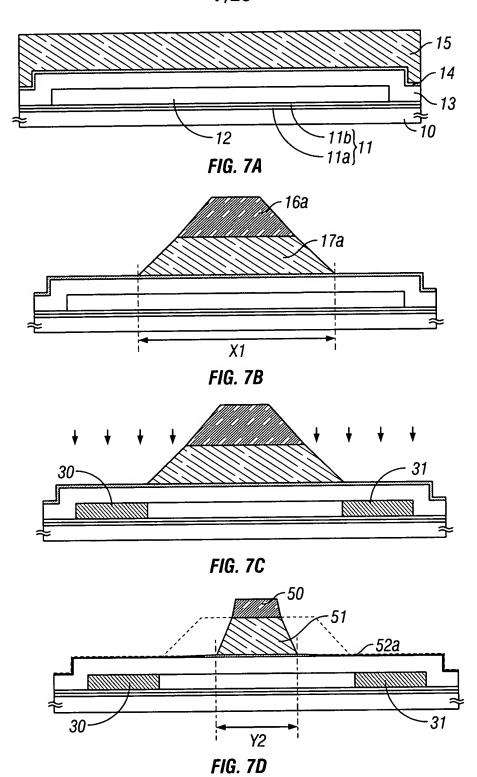
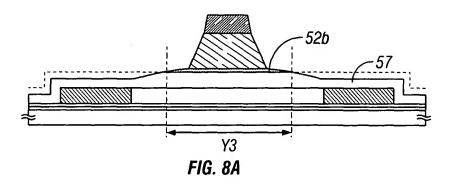
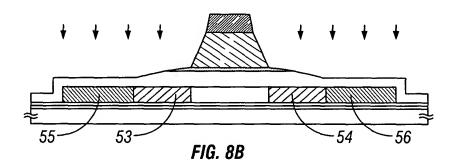


FIG. 6C









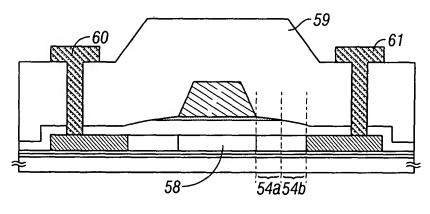
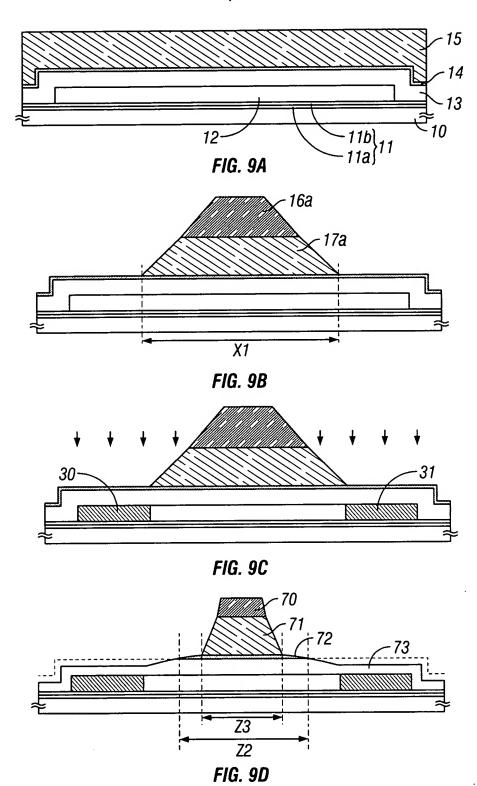


FIG. 8C



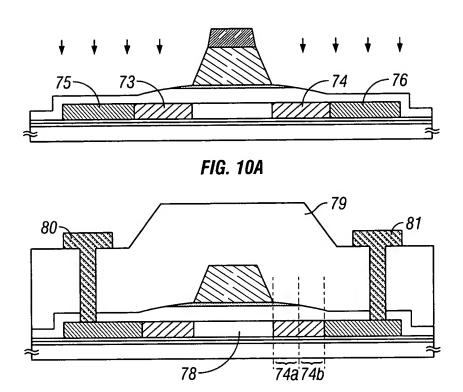
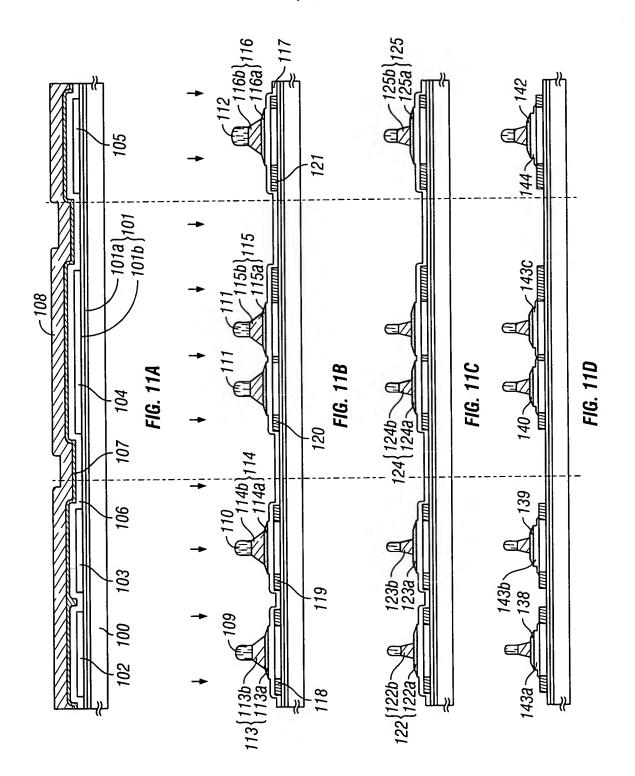
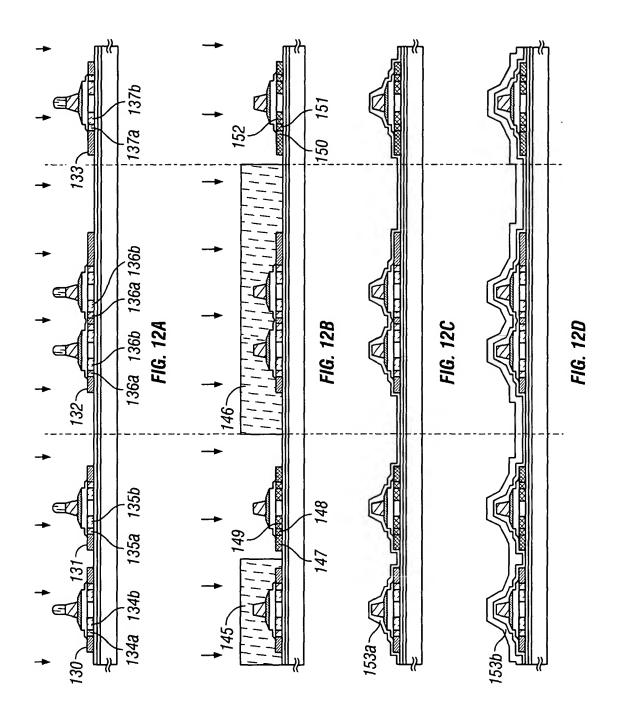


FIG. 10B

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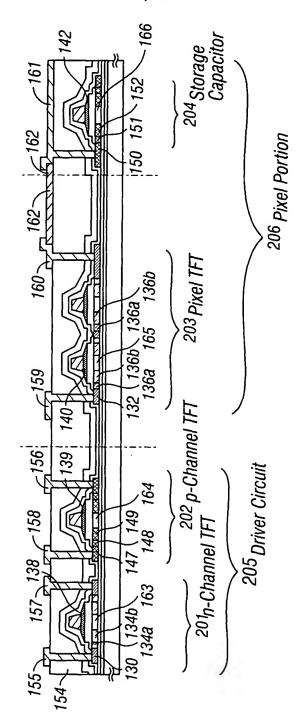
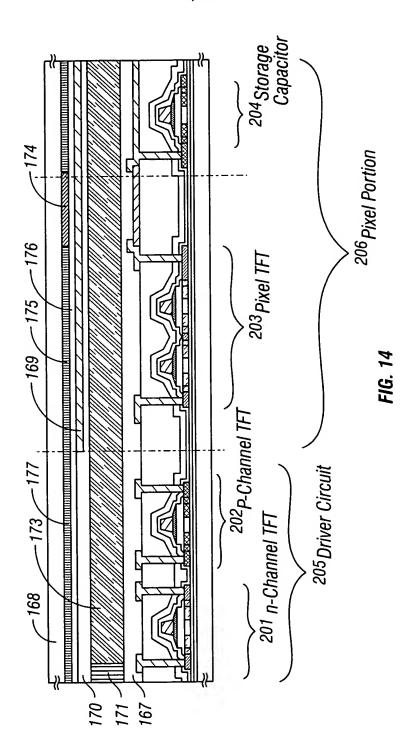


FIG. 13



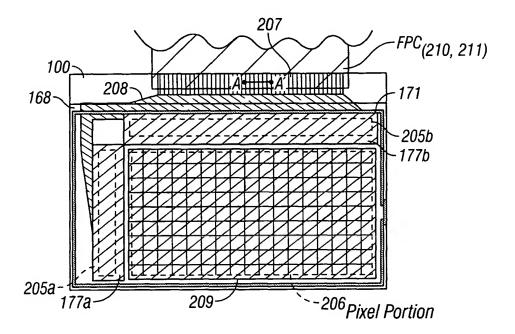
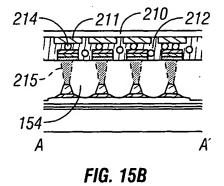
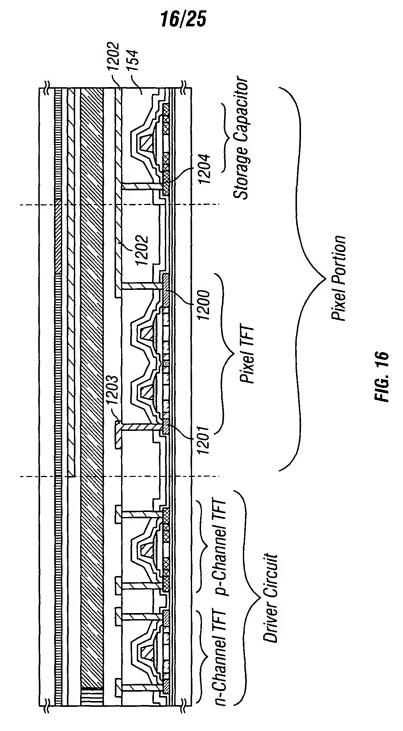


FIG. 15A





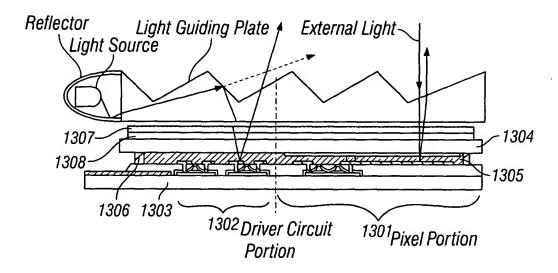


FIG. 17



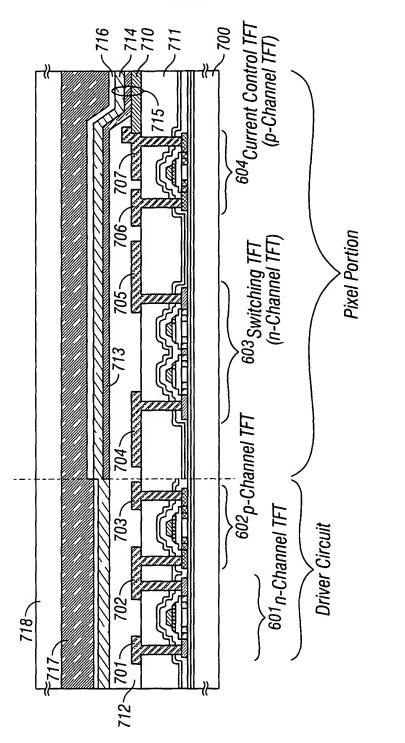
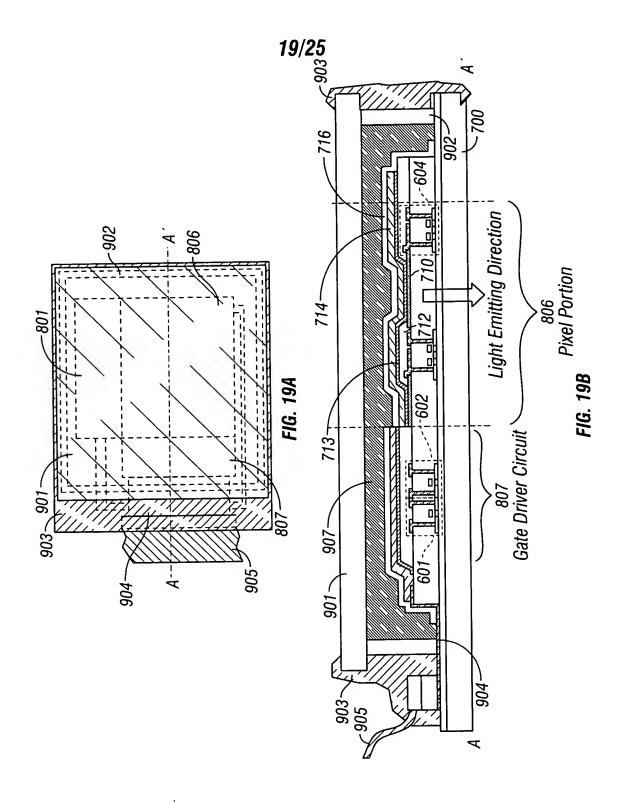
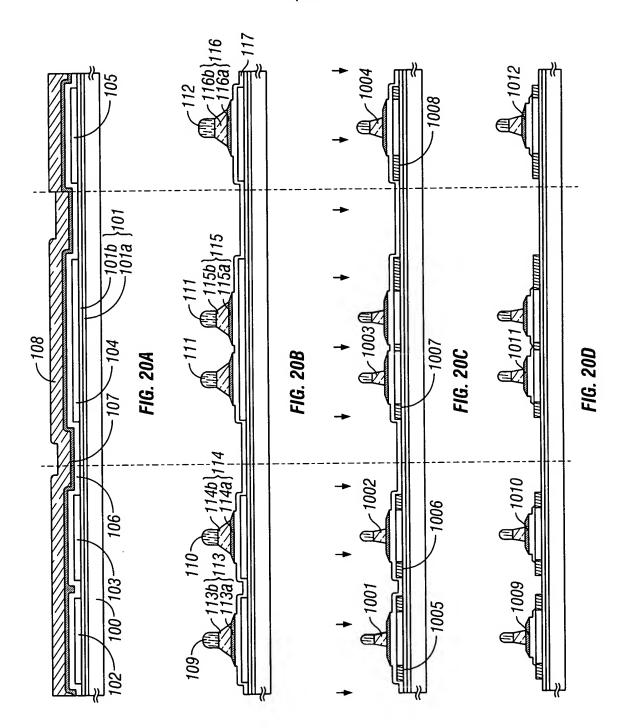
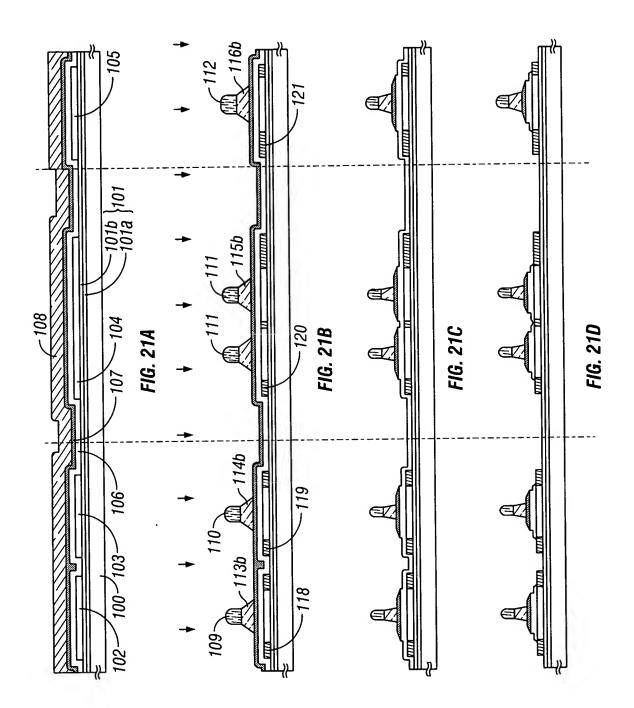


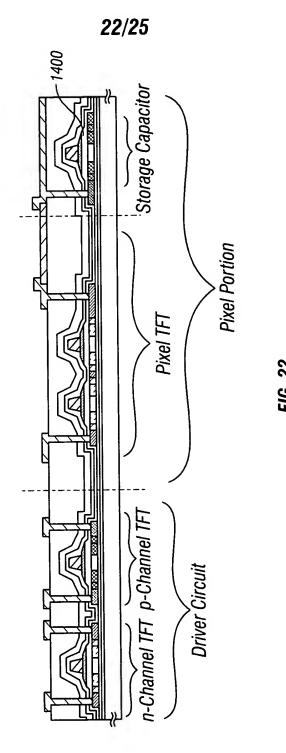
FIG. 18



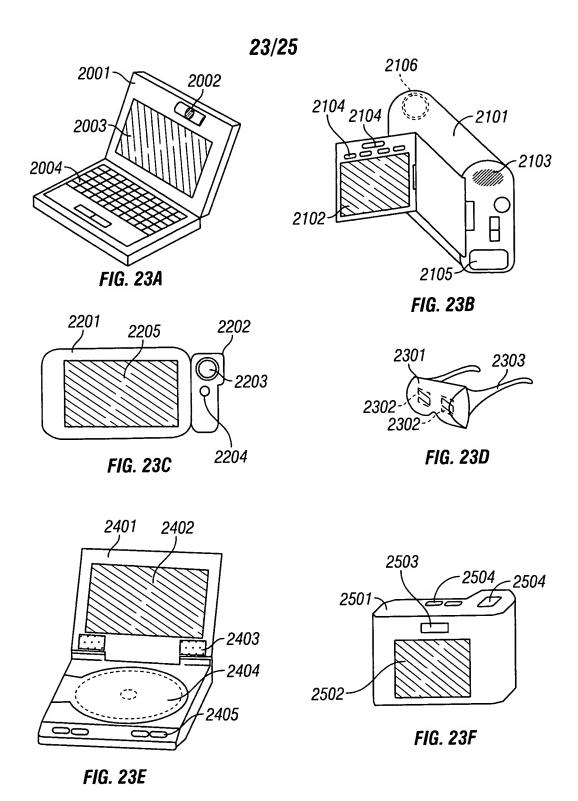


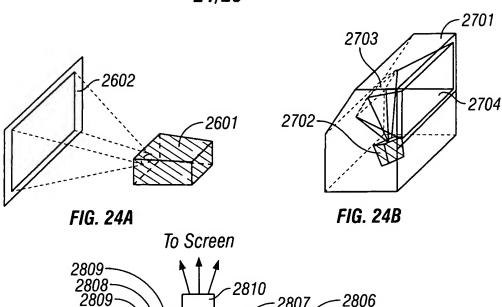
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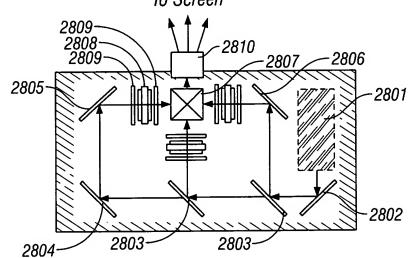


FIG. 24C

2814 2812 2813 2815 2816

FIG. 24D

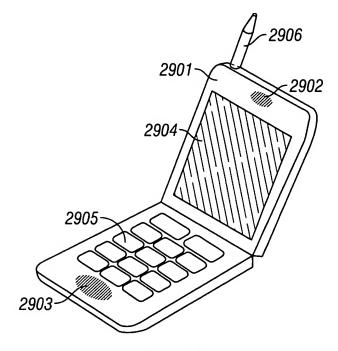


FIG. 25A

3004

3002

3005

3001

FIG. 25B

